Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L17	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
L11	1	"4939568".pn.	USPAT	OR	ON	2005/07/24 16:41
L7	2	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 16:16
L4	3	("5753536" | "5902118" | "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 14:36
L5	3	("5753536" | "5902118" | "6322903").PN. OR ("6525415"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 14:37
L14	7	("4285780" | "5072075" | "5274912" | "5590461").PN. OR ("5706578"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
L6	8	("4461922" | "4481378" | "5398200" | "5401983" | "5612552" | "5731621" | "5747846" | "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 14:38
L15	9	("3489954" | "3533023" | "4939568" | "5311059" | "5401687" | "5438212" | "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
L13	46	("20020050635"|"20020077467"|"20020109236"|"20020109236"|"20020135062"|"4313126"|"4402761"|"4456888"|"4599704"|"4313126"|"4402761"|"4456888"|"4599704"|"4986861"|"5523628"|"5706578"|"5767009"|"5825080"|"0050635"|"5156997"|"5206186"|"5445994"|"5523628"|"5821138"|"5923087"|"6717244"|"6441478"|"6717244"|"0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 20:40
L18	61	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 20:41
L10	68	interconnect near3 copper with transistor	USPAT	OR	ON	2005/07/24 16:40
L16	88	("3787252" | "4074342" | "4500905" | "4523211" | "4688069" | "4761681" | "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40

L3	123	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 20:41
L9	135	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 16:17
L8	190	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 16:16
L2	1094	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 14:31